# ON3100

## **Optoisolator**

## ■ Outline

The ON3100 is a high transfer ratio optoisolator. Dark current is small and stable transfer ratio is obtained against temperature fluctuation as high power GaAs infrared light emitting diode and high sensitive Si phototransistor are used for light emitting device and receiving device, respectively.

## **■** Features

• High CTR: CTR>50%

• High V<sub>ISO</sub>: V<sub>ISO</sub>=2500V (AC)

• Fast response:  $t_r$ ,  $t_t = 5\mu s$  (typ.)

• Low CTR charge against fluctuation in temperature

• UL recognized File No. E79920 (M)

#### ■ Use

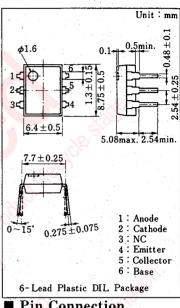
Solid state relay

• Elimination of ground loop and EMI/RFI problems associated differential ground.

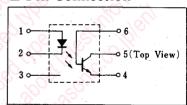
	Item	Symbol	Value	Unit
	Reverse Voltage (DC)	V <sub>R</sub>	3	V
Input (Light Emitting Diode)	Forward Current (DC)	I <sub>F</sub>	50	mA
	Pulse Forward Current	I <sub>FP</sub> *1	2	Α
	Power Dissipation	P <sub>D</sub> *2	75	mW
Output (Photo Transistor)	Collector Current	Ic	50	mA
	Collector to Emitter Voltage	V <sub>CEO</sub>	30	Z CV
	Collector to Base Voltage	V <sub>CBO</sub>	35	V
	Emitter to Base Voltage	V <sub>EBO</sub>	5	V
	Emitter to Collector Voltage	V <sub>ECO</sub>	5 😠	V
	Collector Power Dissipation	Pc*3	120	mW
Total Power Dissipation		P <sub>T</sub>	150	mW
Operating Am	bient Temperature	Topr	$-25 \sim +85$	°C
Storage Temp	perature	T <sub>stg</sub>	$-40 \sim +100$	°C

## ■ Recommended Operating Conditions

Item	Symbol	min.	typ.	max.	Unit
Supply Voltage (collector supplying voltage)	Vcc		5~24		V
Input Forward Current	$I_{\mathbf{F}}$		5~20		mA



## ■ Pin Connection



- \*1 Pulse width 1  $\mu$ s, repeat 300 pps.
- \*2 Derate (1.0 mW/°C) above 25°C ambient
- Derate (1.6 mW/°C) above 25°C ambient

■ Electro-Optical Characteristics (Ta=25°C)

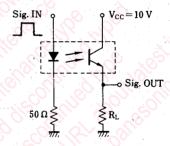
Item		Symbol	Condition	min.	typ.	max.	Unit
Input Characteristics	Reverse Current (DC)	I <sub>R</sub>	$V_R = 3 \text{ V}$			10	μA
	Forward Voltage (DC)	V <sub>F</sub>	$I_F = 50 \text{ mA}$		1.25	1.5	V
	Capacitance between Terminals	Ct	$V_R = 0$ , $f = 1 MHz$		30		pF
Output Characteristics	Collector Cutoff Current	I <sub>CEO</sub>	V <sub>ce</sub> =10 V		10	200	nA
	Collector to Emitter Voltage	V <sub>CEO</sub>	$I_c = 100 \mu\text{A}$	30	50		V
	DC Current Amplification Factor	h <sub>FE</sub>	$V_{CE}=5 \text{ V}, I_{C}=2 \text{ mA}$		500		
	Collector Output Capacitance	Çc	$V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$		10		pF
Coupled Characteristics	DC Current Transfer Ratio	CTR*1*3	$V_{CE} = 10 \text{ V}, I_F = 5 \text{ mA}$	50		600	%
	Input/Output Breakdown	V <sub>ISO</sub> *2	t=lmin, RH<60 %	DC3000 AC2500		0	V
	Input/Output Capacity	C <sub>iso</sub>	f=1 MHz		0.5	<b>9</b>	pF
	Input/Output Resistance	R <sub>iso</sub>	V <sub>ISO</sub> =500 V	1011	100		Ω
	Response Time	tr, tf *2*4	$V_{cc} = 10 \text{ V}, I_c = 5 \text{ mA}, R_L = 100 \Omega$	.0	5		μs
	Collector Saturation Voltage	V <sub>CE(sat)</sub>	$I_F = 5 \text{ mA}, I_C = 1 \text{ mA}$	1111		0.4	V

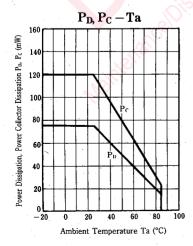
<sup>\*1</sup> DC current transfer ratio (CTR) is a ratio of output against DC input current.

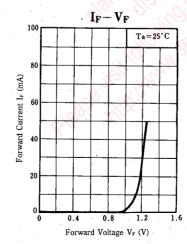
## \*3 CTR Classification

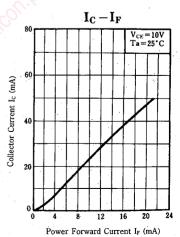
Class	Q	R	S
CTR	50~120%	100~250%	200~600%

## \*4 Measuring circuit for response characteristics

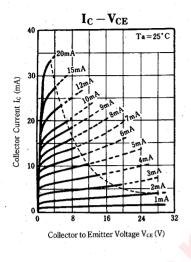


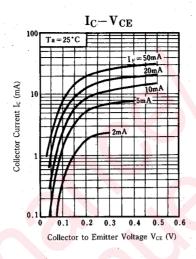


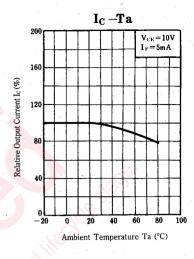


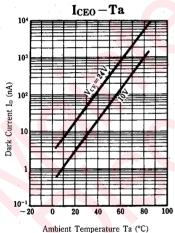


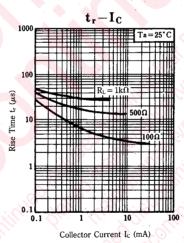
<sup>\*2</sup> Rise time (Time required for the collector current to increase from 10% to 90% of its final value)
Fall time (Time required for the collector current to decrease from 90% to 10% of its final value)

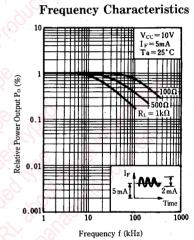












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